

PMP10175 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	470pF	C3216C0G2J471J	TDK	CAP, CERM, 470 pF, 630 V, +/- 5%, C0G/NP0, 1206	1206
C3, C4	2	4.7uF	ESH475M450AH2AA	Kemet	CAP, AL, 4.7 μF, 450 V, +/- 20%, TH	10x15mm
C5	1	0.1uF	ECQ-U2A104ML	Panasonic	CAP, Film, 0.1 μF, 275 V, +/- 20%, TH	17.5x5.5x12.5mm
C6	1	470uF	EEE-FK0J471P	Panasonic	CAP, AL, 470 μF, 6.3 V, +/- 20%, 0.16 ohm, SMD	SMT Radial F
C7	1	10uF	C2012X7R0J106M125AB	TDK	CAP, CERM, 10 μF, 6.3 V, +/- 20%, X7R, 0805	0805
C8	1	0.1uF	C1608X7R1H104K	TDK	CAP, CERM, 0.1 μF, 50 V, +/- 10%, X7R, 0603	0603
C100	1	220pF	C1608C0G1H221J	TDK	CAP, CERM, 220 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
D3, D4, D7, D8	4	1000V	1N4007	Fairchild Semiconductor	Diode, P-N, 1000 V, 1 A, TH	DO-41
D5	1	600V	STTH1R06A	ST Microelectronics	Diode, Ultrafast, 600 V, 1 A, SMA	SMA
D6	1	40V	MBRA340T3G	ON Semiconductor	Diode, Schottky, 40 V, 3 A, SMA	SMA
J1, J2	2	Jumper wire	Jumper wire	3M	Jumper wire	300mil spacing jumper
L1	1	1mH	7447462102	Würth Elektronik eiSos	Inductor, Unshielded Drum Core, Ferrite, 1 mH, 0.25 A, 4.38 ohm, TH	D6 x 8.5mm
R1	1	100k	CRCW1206100KJNEA	Vishay-Dale	RES, 100 k, 5%, 0.25 W, 1206	1206
R3	1	88.7k	CRCW060388K7FKEA	Vishay-Dale	RES, 88.7 k, 1%, 0.1 W, 0603	0603
R5	1	22.1k	CRCW060322K1FKEA	Vishay-Dale	RES, 22.1 k, 1%, 0.1 W, 0603	0603
RF1	1	10	PWR4522AS10R0JA	Bourns	RES, 10, 5%, 3 W, Fusible, TH	Axial
RV1	1	275V	S10K275E2	EPCOS Inc	Varistor 275V RMS 10MM Radial, TH	10mm Radial
T1	1	10 mH	750315313	Würth Elektronik eiSos	Transformer, 10 mH, SMT	17.75x13.46mm
TP3, TP5	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
TP4	1	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP6	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		UCC28880DR	Texas Instruments	700-V Lowest Quiescent Current Off-Line Switcher, D0007A	D0007A

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